DESCRIPTION

The US2AA~US2MA are available in SMA package

FEATURES

- For surface mounted applications
- Low profile package
- Glass Passivated Chip Junction
- Easy to pick and place
- High efficiency
- Available in SMA package

ORDERING INFORMATION

Package Type	Part Number				
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	US2AA				
SMA	US2BA				
	US2DA				
	US2GA US2JA				
					US2KA
	US2MA				
	Note	SPQ: 3,000pcs/Reel			
AiT provides all RoHS Compliant Products					

MECHANICAL DATA

Case: SMA

Terminals: Solderable per MIL-STD-750,

Method 2026

Approx. Weight: 0.055g / 0.002oz

PIN DESCRIPTION





MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25 ambient temperature unless otherwise specified. Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter		Symbol	US2AA	US2BA	US2DA	US2GA	US2JA	US2KA	US2MA	Unit
Maximum Repetitive Peak		V_{RRM}	50	100	200	400	600	800	1000	V
Reverse Voltage		VRRM	30	100	200	400	000	800	1000	V
Maximum RMS Volta	Maximum RMS Voltage		35	70	140	280	420	560	700	V
Maximum DC Blockir	Maximum DC Blocking Voltage			100	200	400	600	800	1000	V
Maximum Average Forward		I _{F(AV)}				2.0				Α
	Rectified Current at T _C =125°C									
_	Peak Forward Surge Current									
8.3ms Single Half Sine Wave		I _{FSM}	70							Α
Superimposed on Ra	Superimposed on Rated Load									
Maximum Instantaneous		VF		1.0 1.3			1.65			V
Forward Voltage at 2A				1.0		1.5		1.00		v
Maximum DC										
Reverse Current at	T _A =25°C		5.0 100							μΑ
Rated DC	T _A =125°C	I _R								
Blocking Voltage										
Maximum Reverse R	aximum Reverse Recovery		t _{rr} 50 75							no
Time ^{NOTE1}		C rr							ns	
Typical Thermal Resistance ^{NOTE2}		Reja	65					°0.047		
		Rеjc	20						°C/W	
Operating and Storage		т т	55 450						°C	
Temperature Range		T _J , T _{STG} -55 ~150							10	

NOTE1: Measured with I_{F} = 0.5 A, I_{R} = 1 A, I_{rr} = 0.25 A

NOTE2: P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper pad areas.

TYPICAL CHARACTERISTICS

Figure. 1 Forward Current Derating Curve

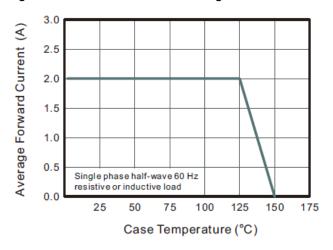


Figure. 3 Typical Forward Characteristics

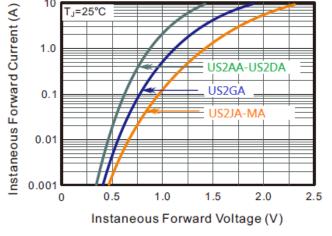


Figure. 2 Typical Reverse Characteristics

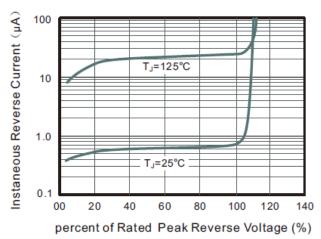
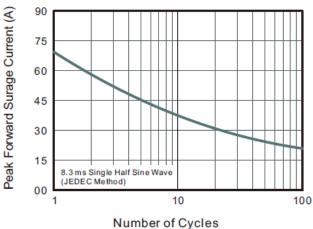


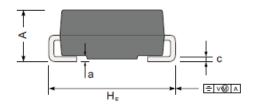
Figure. 4 Maximum Non-Repetitive Peak Forward Surge Current

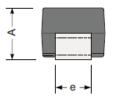


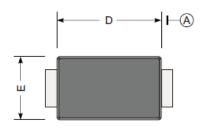
PACKAGE INFORMATION

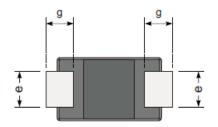
Dimension in SMA (Unit: mm)

Plastic surface mounted package; 2 leads

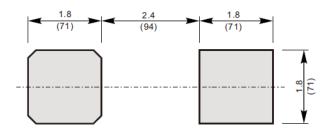








The recommended mounting pad size



Unit :
$$\frac{mm}{(mil)}$$

UNIT		Α	D	E	HE	С	е	g	а
	Max	2.2	4.5	2.7	5.2	0.31	1.6	1.5	0.3
mm	Min	1.9	4.0	2.3	4.7	0.15	1.3	0.9	
mil	Max	87	181	106	205	12	63	59	40
	Min	75	157	91	185	6	51	35	12



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